

08-31-1998

PATENTS F



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To the Honorable Commissioner of Patents and Trademarks: Please record the attached original document or copy thereof.

1. Names of conveying party(ies):

Takahisa YAMAHA
Tetsuya KUWAJIMA

Individuals

Additional names(s) of conveying party(ies) attached? NO

2. Name and Address of receiving party(ies):

Yamaha Corporation
10-1, Nakazawa-cho, Hamamatsu-shi
Shizuoka, Japan

Corporation of Japan

Additional name(s) & address(es) attached? NO

3. Nature of conveyance: **MRD 8-24-98**

Assignment

Execution Date: **July 30, 1998**

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: July 30, 1998

A. Application No.(s)

B. Patent No.(s)

09/138552

Additional numbers attached? NO

5. Name and address of party to whom
correspondence concerning document should
be mailed:OSTROLENK, FABER, GERB & SOFFEN, LLP
1180 Avenue of the Americas
New York, New York 10036-8403

6. Total number of documents involved: 1

7. Total fee (37 CFR 3.41): \$ 40.00

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8. *To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.***Max Moskowitz**

Name of Person Signing

Signature

August 24, 1998

Date

Total number of pages including cover sheet, attachments, and document: 2

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PATENT

REEL: 9407 FRAME: 0233

PATENT APPLICATION ASSIGNMENT -
SOLE OR JOINT INVENTORS
EXECUTED OUTSIDE U.S.A.

OFGS FILE NO.

P/2171-136 (-)

WHEREAS, I (We), Takahisa YAMAHA, and Tetsuya KUWAJIMA
as assignor(s), have invented certain improvements in
METHOD OF MANUFACTURING WIRING STRUCTURE HAVING BURIED PLUGS IN
SEMICONDUCTOR DEVICE, AND SEMICONDUCTOR DEVICE for
which an application for United States Letters Patent has been executed by me (us) of even
date herewith; and

WHEREAS, YAMAHA CORPORATION
10-1, Nakazawa-cho, Hamamatsu-shi,
Shizuoka, Japan
as assignee, is desirous of acquiring all right, title and interest in and to said invention
and any Patent that may be granted therefor.

NOW, THEREFORE, in consideration of One Dollar (\$1.00) and other good and
valuable consideration, the receipt of which is hereby acknowledged, I (We), as assignor(s),
hereby sell, assign and set over to said assignee the entire right, title and interest for
the United States and all other countries in and to said invention and the aforesaid
application for Patent, all original, divisional, continuation, substitute or reissue
applications and patents applied for or granted therefor in the United States and all other
countries, including all rights of priority from the filing of said application, and all
rights for past infringement, and the Commissioner of Patents and Trademarks is hereby
authorized and requested to issue all patents on said inventions or resulting therefrom to
said assignee herein, as assignee of the entire interest therein; and the undersigned for
myself (ourselves) and my (our) legal representatives, heirs and assigns do hereby agree and
covenant without further remuneration, to execute and deliver all divisional, continuation,
reissue and other applications for Patent on said inventions and all assignments thereof to
said assignee or its assigns, to communicate to said assignee or its representatives all
facts known to the undersigned respecting said inventions, whenever requested, to testify in
any interferences or other legal proceedings in which any of said applications or patents may
become involved, to sign all lawful papers, make all rightful oaths, and to do generally
everything necessary to assist assignee, its successors, assigns and nominees to obtain
patent protection for said invention in the United States and all other countries, the
expenses incident to said applications to be borne and paid by said assignee.

Date: July 30, 1998

Takahisa Yamaha
Takahisa YAMAHA

Date: July 30, 1998

Tetsuya Kuwajima
Tetsuya KUWAJIMA

Date: _____

Date: _____

LEGALIZATION RECOMMENDED